

500V Super-Junction Power MOSFET

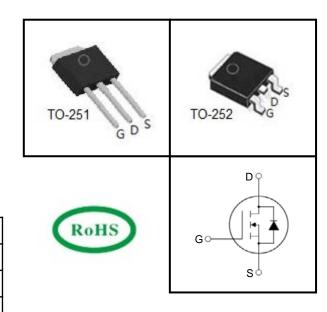
FEATURES

- $\qquad \text{Very low FOM R}_{\text{DS(on)}} \times \text{Q}_{\text{g}}$
- 100% avalanche tested
- RoHS compliant

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Device Marking and Package Information			
Device	Package	Marking	
TPU50R1K5C	TO-251	50R1K5C	
TPD50R1K5C	TO-252	50R1K5C	



Absolute Maximum Ratings $T_C = 25^{\circ}C$, unless otherwise noted					
Barrandar	Ob-al	Comple al	Value		11.74
Parameter		Symbol	TO-251	TO-252	Unit
Drain-Source Voltage (V _{GS} = 0V)		V_{DSS}	500		V
Continuous Drain Current		I _D	2) -	А
Pulsed Drain Current	(note1)	I _{DM}	6	;	А
Gate-Source Voltage		V_{GSS}	±	30	V
Single Pulse Avalanche Energy	(note2)	E _{AS}	1:	2	mJ
Avalanche Current	(note1)	I _{AR}	0.	5	А
Repetitive Avalanche Energy (note1)		E _{AR}	0.05		mJ
Power Dissipation (T _C = 25°C)		P_D	17.8		W
Operating Junction and Storage Temperature Range		T_J,T_stg	-55~-	+150	°C

Thermal Resistance				
Baramatan	Value		lue	Unit
Parameter	Symbol	TO-251 TO		
Thermal Resistance, Junction-to-Case	R _{thJC}	7	.0	12/00/
Thermal Resistance, Junction-to-Ambient	R _{thJA}	6	2	K/W



Parameter	Symbol	To al Constituion o	Value			
		Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	500			V
Zoro Coto Voltago Drain Current		$V_{DS} = 500V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 500V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 30V$			±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.5		4.0	V
Drain-Source On-Resistance (Note3)	R _{DS(on)}	V _{GS} = 10V, I _D = 1A		1.3	1.5	Ω
Forward Transconductance (Note3)	g _{fs}	V _{DS} = 10V, I _D = 1A		2		S
Dynamic						
Input Capacitance	C _{iss}	V 9V		174		pF
Output Capacitance	C _{oss}	$V_{GS} = 0V,$ $V_{DS} = 50V,$		10		
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		1.5		
Total Gate Charge	Q_g	$V_{DD} = 480V, I_{D} = 2A,$ $V_{GS} = 10V$		5.3		nC
Gate-Source Charge	Q_{gs}			1		
Gate-Drain Charge	Q_{gd}			2.7		
Turn-on Delay Time	t _{d(on)}			30		
Turn-on Rise Time	t _r	$V_{DD} = 400V, I_{D} = 2A,$		29		
Turn-off Delay Time	t _{d(off)}	$R_G = 25\Omega$		54		ns
Turn-off Fall Time	t _f			31		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	Is	T 0500			2	^
Pulsed Diode Forward Current	I _{SM}	T _C = 25°C			6	Α
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}\text{C}, I_{SD} = 2\text{A}, V_{GS} = 0\text{V}$		0.9	1.2	V
Reverse Recovery Time	t _{rr}	$V_R = 480V, I_F = I_S, di_F/dt = 100A/\mu s$		150		ns
Reverse Recovery Charge	Q _{rr}			0.5		μC
Peak Reverse Recovery Current	I _{rrm}			6.0		А

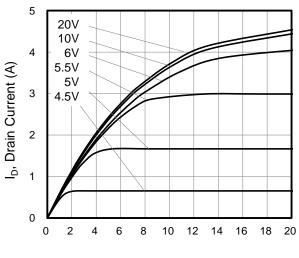
Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. I_{AS} = 1.5A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%



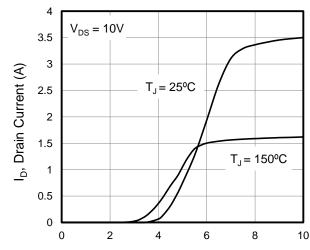
Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

Figure 1. Output Characteristics



V_{DS}, Drain-to-Source Voltage (V)

Figure 2. Transfer Characteristics



V_{GS}, Gate-to-Source Voltage (V)

Figure 3. On-Resistance vs. Drain Current

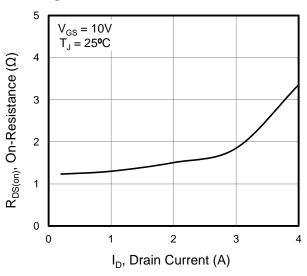


Figure 5. Gate Charge

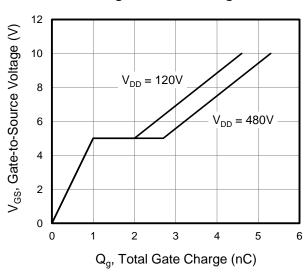


Figure 4. Capacitance

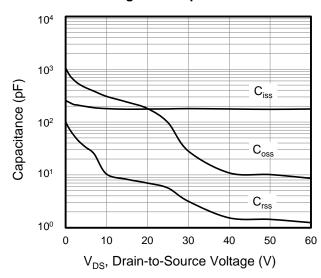
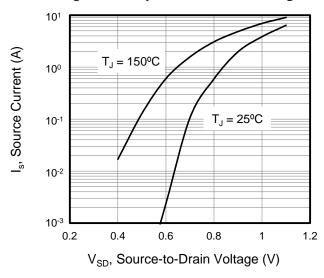


Figure 6. Body Diode Forward Voltage





Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Figure 7. On-Resistance vs.

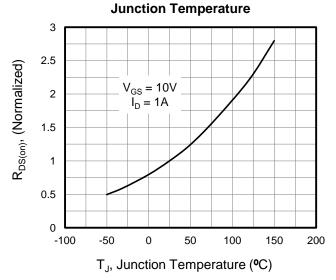


Figure 9. Transient Thermal Impedance TO-251/TO-252

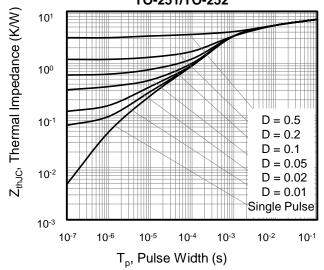


Figure 8. Threshold Voltage vs. Junction Temperature

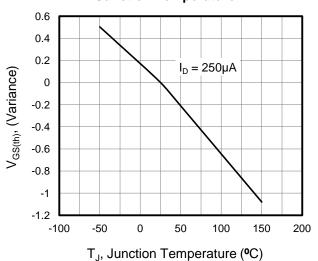




Figure A: Gate Charge Test Circuit and Waveform

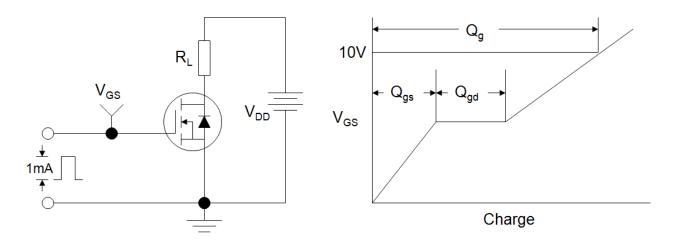


Figure B: Resistive Switching Test Circuit and Waveform

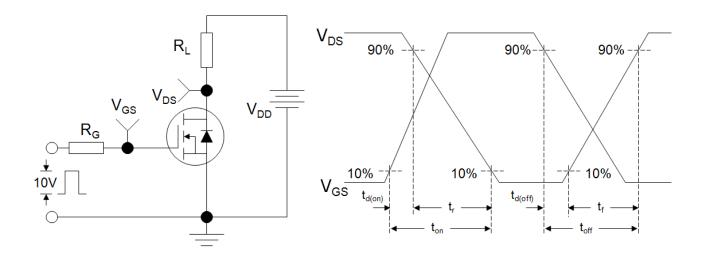
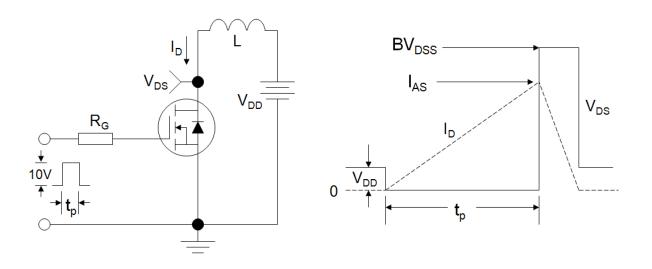
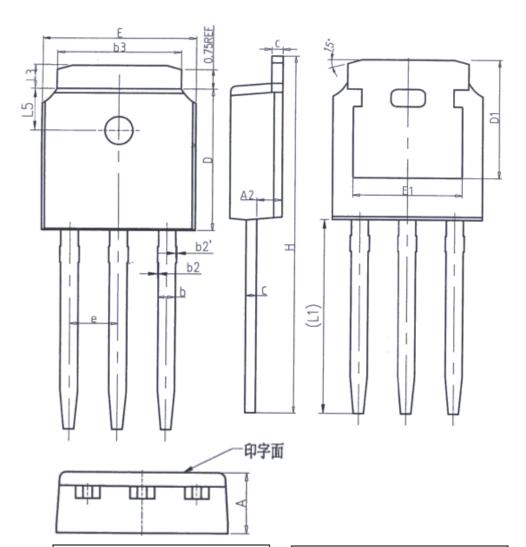


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



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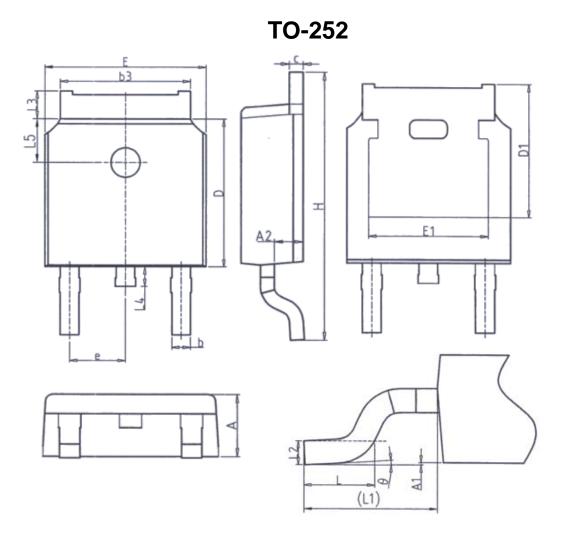
TO-251



Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b2	0.00	0.10	
b2′	0.00	0.10	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	

Unit: mm			
Symbol	Min.	Max.	
D1	5. 30	REF	
E	6. 40	6. 80	
E1	4. 63	-	
е	2. 286BSC		
Н	16. 22	16. 82	
L1	9. 15	9. 65	
L3	0.88	1. 28	
L5	1. 65	1. 95	





Unit: mm			
Symbol	Min.	Max.	
Α	2. 20	2. 40	
A1	0.00	0. 20	
A2	0. 97	1. 17	
b	0. 68	0. 90	
b3	5. 20	5. 50	
С	0. 43	0. 63	
D	5. 98	6. 22	
D1 5. 30REF			
E	6. 40	6. 80	
E1	4. 63	-	

Unit: mm			
Symbol	Min.	Max.	
е	2. 28	6BSC	
Н	9. 40	10.50	
L	1. 38	1. 75	
L1	2. 90REF		
L2	0. 51BSC		
L3	0.88	1. 28	
L4	- 1.00		
L5	1. 65	1. 95	
θ	0°	8°	



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